

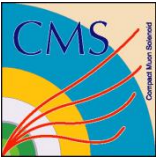


CMS HL-LHC EM Calorimeter Upgrade

M. Hansen, CERN



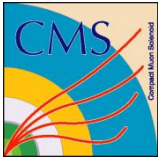
ECAL barrel Phase 2 Upgrade Requirements



- **Trigger rate up to 750 kHz**
 - ◆ **Legacy max ~150 kHz**
- **Trigger latency up to 12.5 us**
 - ◆ **Legacy max ~5 us**
- **Full installation during LHC Long Shutdown 3**
- **Maintained or improved reliability and availability**
- **Improved ECAL spike detection and mitigation**
- **Front End specific**
 - ◆ **Magnetic field tolerant (4T)**
 - ◆ **Radiation tolerant ~5Mrad (1 Mrad expected)**



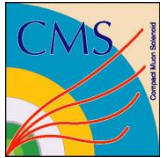
ECAL barrel Phase 2 Upgrade High on the wish list



- **Re-optimize front end ASIC parameters in order to maintain performance despite crystal and APD degradation due to radiation damage**
- **Decrease the physical volume required for services on YB0**
 - ◆ E.g. by decreasing the Low Voltage Current delivered to the Front End and thus use thinner or less cables
 - ◆ E.g. by decreasing power consumption in the front end and thus use thinner cooling lines
- **Review front end grounding and shielding scheme in order to make the system less sensitive to EMI**
- **Solid failure mitigation scheme**
 - ◆ E.g. avoid dependence between neighbours



Phase 2 ECAL Barrel FE electronics system - Design idea



- **Modularity**

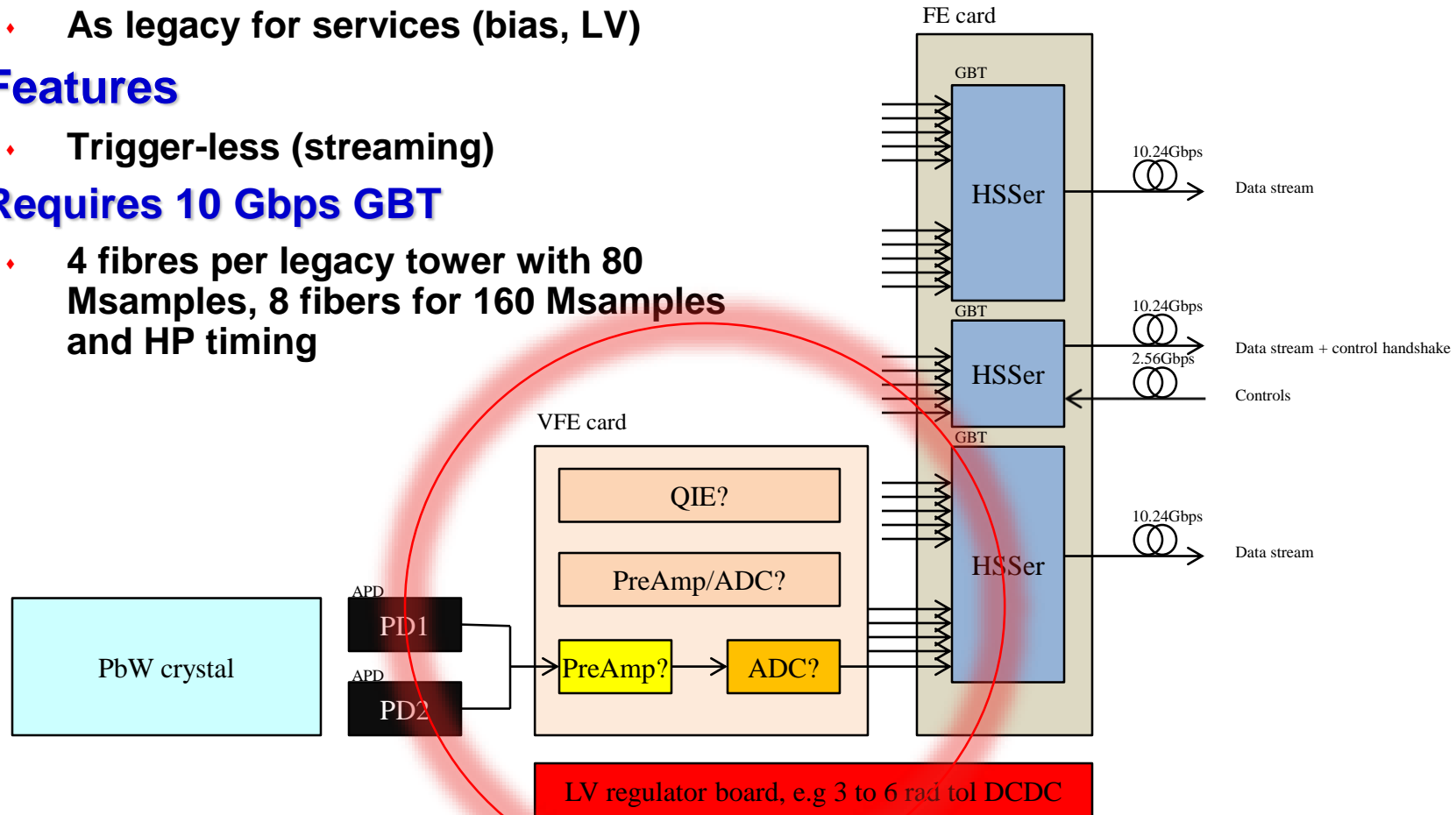
- ◆ 1 channel for readout and trigger
- ◆ As legacy for services (bias, LV)

- **Features**

- ◆ Trigger-less (streaming)

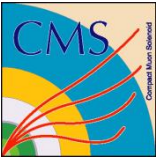
- **Requires 10 Gbps GBT**

- ◆ 4 fibres per legacy tower with 80 Msamples, 8 fibers for 160 Msamples and HP timing





External constraints



- **YB0 and YE1+- services will be completely removed early in LS3**
 - ◆ **Cables, fibres and pipes cut in 1m pieces by a team without silk gloves and discarded**
- **As a consequence essentially all cables between UXC55 and USC55 will have to be replaced**
 - ◆ **Essentially fibers and HV cables for the EB**
- **One full year for 36 Supermodule removal, re-work, and re-installation**



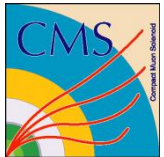
Internal constraints



- **Modularity**
 - ◆ 25 readout channels organized as 5 phi strips
 - ◆ APD and low voltage connectors fully defined
- **VFE and LVRB form factor known**
 - ◆ 3D limits including hard connection to cooling system
 - ◆ Motherboard (APD) connector fully defined
 - ◆ Need good reasons to change the FE connector
- **FE form factor known**
 - ◆ 2D limits
 - ◆ Again, need good reasons to change the VFE connector
- **Power budget within legacy limits, essentially 2W per channel; Goal perfectly within reach is 1W per channel**



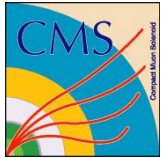
External aid



- **Applicable and useful common developments**
 - ◆ **IpGBT @ 10.24 / 2.56 Gbps**
 - Development ongoing, cost estimated to 35 CHF
 - ◆ **Versatile link +**
 - Development ongoing, cost estimated to 100 USD per connection (rad hard optics plus fiber, OD parts excluded)
 - ◆ **Low voltage regulator**
 - Radiation and magnetic field tolerant DCDC converter in production, development of enhanced ASIC ongoing, module available for 35 CHF
 - ◆ **Radiation tolerance qualified tool kit for TSMC 130nm and 65nm available**
 - Including e.g. eLink macros for ADC – GBT integration
- **CMS ECAL may want to contribute to these multi-institutional / multi-national projects**



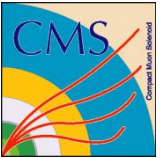
Development Timeline



- **Kick-off about a year ago**
- **This workshop**
 - ◆ **Essentially about VFE specification and strategy for technology selection**
- **Comprehensive review June 2016**
 - ◆ **Essentially a report from this workshop and current actions**
- **December 2016**
 - ◆ **Baseline VFE design**
 - ◆ **Demonstration of FE DCDC power feasibility**
- **September 2017**
 - ◆ **TDR**
 - ◆ **Here we have to demonstrate that we know what we need, what to do and that the resources are sufficient to deliver the project on time**



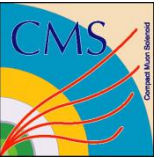
LpGBT



- **Down-link: 2.56 Gb/s (64 –bit frame)**
 - ◆ **User bandwidth with FEC12: 1.44 Gb/s or 36 bits / 40MHz clock**
- **Up-link: 10.24 Gb/s (256 –bit frame)**
 - ◆ **User bandwidth**
 - FEC12: 8 Gb/s
 - FEC5: 9.13 Gb/s
- **Phase/Frequency programmable clocks**
 - ◆ **4 independent clocks with 50ps phase resolution**
 - ◆ **Frequencies: 40 / 80 / 160 / 320 / 640 / 1280 MHz**



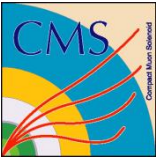
LpGBT



- **ASIC control: IC channel: 80 Mb/s**
 - ◆ **I2C interface**
 - LpGLD control:I2C master
- **Experiment control: EC channel: 80 Mb/s**
 - ◆ **Two I2C masters**
 - ◆ **Programmable parallel port:16 x DIO**
 - ◆ **Environmental parameters monitoring**
 - 10-bit ADC with 8 inputs
 - Temperature sensor on chip
 - Programmable current source to drive an external temperature sensor
- **Replaces the current GBT-SCA**



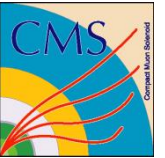
Link and bit counts



- **eLinks FEC5 @ 10.24 Gb/s**
 - ◆ **Bandwidth: 320 / 640 / 1280 Mb/s**
 - 8 / 16 / 32 bits per 40 MHz clock
 - ◆ **# eLinks*: 28 / 14 / 7**
- **eLinks FEC12 @ 10.24 Gb/s**
 - ◆ **Bandwidth: 320 / 640 / 1280 Mb/s**
 - 8 / 16 / 32 bits per 40 MHz clock
 - ◆ **# eLinks*: 24 / 12 / 6**
- **eLink Macro exists for TSMC 130nm and 65nm**



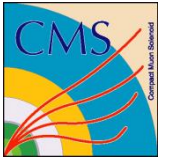
Link and bit counts



- **Three 10 Gbit up-links would allow 24 (26) bits per channel**
 - ◆ Three 320 Mbit Elinks
 - ◆ 11 (12) bits ADC plus gain flag @ 80MHz. Enough?
 - ◆ Requires e.g. one 3+1 versatile link+ module per FE (foreseen)
- **Four 10 Gbit up-links would allow 32 (34) bits per channel**
 - ◆ Four 320 Mbit or two 640 Mbit or one 1280 Mbit Elinks
 - ◆ 15 (16) bits ADC plus gain flag @ 80MHz. Better?
 - ◆ Requires e.g. one 4+1 versatile link+ module per FE (foreseen)
- **Six 10 Gbit up-links would allow 48 (52) bits per channel**
 - ◆ Six 320 Mbit or three 640 Mbit Elinks
 - ◆ 11 (12) bits ADC plus gain flag @ 160MHz.
 - ◆ 15 (16) bits ADC plus gain flag @ 120MHz.
 - ◆ Requires e.g. two 3+1 versatile link+ module per FE
 - Only one FE control link would be used; the other receiver used for precision sampling clock?



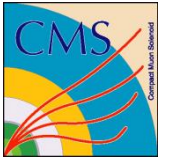
VFE to FE Data transmission



- **Implement a number of eLinks in every ADC / QIE for data streaming**
 - ♦ **A few idle characters required in order to word-align at reception in the off detector electronics**
 - E.g. upon BC0 reception; note that the arrival time of the BC0 needs to be skewed together with the clock or at least dealt with
 - Imagine e.g. an all zeros – all ones – all zeros transition as ADC response to the BC0



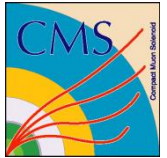
LVRB replacement



- **A radiation and magnetic field tolerant ACDC power module has been developed which meets, a priori, our electrical requirements**
 - ◆ **Investigate noise levels with an initial demonstrator; essentially done**
 - ◆ **Verify behavior in radiation and magnetic field; started**
 - ◆ **Develop LVRB respecting the mechanical requirements; first version essentially ready**



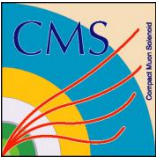
Bulk power system



- **Essentially all LHC upgrade projects are planning to use DCDC POL converters in or close to the front end system**
- **The DCDC converters developed to date allow up to 12V input, essentially non-regulated.**
- **A common project, similar to the legacy, is started in order to investigate the feasibility of operating COTS bulk power supplies**
 - ◆ **In the service cavern**
 - Radiation level as essentially zero
 - Magnetic field 50 – 100 Gauss
 - ◆ **In the experimental cavern, e.g. X0**
 - Radiation level as essentially as in service cavern
 - Magnetic field 200 – 400 Gauss; balconies essentially excluded: up to 1200 Gauss



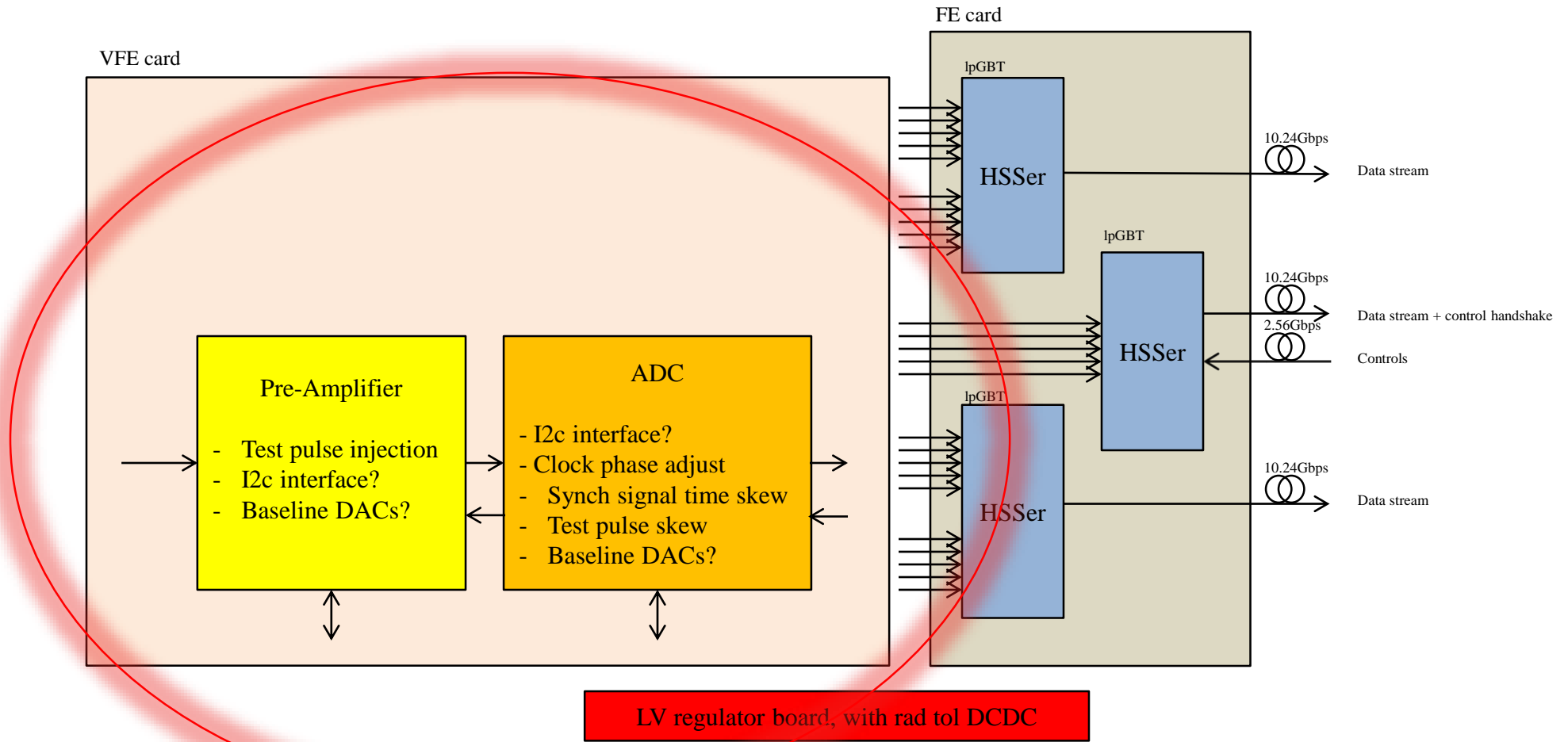
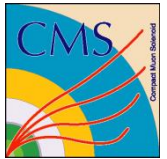
Bias (HV) power system



- **Essentially, the requirements have not changed, thus the HV power system can be maintained.**
 - ◆ **The key word is “maintained” rather than “kept”**
 - ◆ **The complete system will very likely need to be renewed purely due to age**
- **Profit from the complete YB0 de-installation to review the grounding and shielding implementation in order to become less sensitive to EMI**

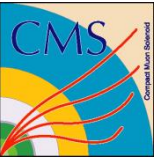


Phase 2 ECAL Barrel FE electronics system



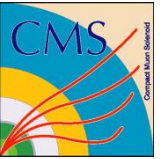


End



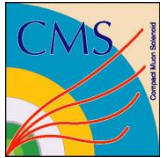


Backup





FE clock distribution



- **Option 1**
 - ◆ Use the (non-skewable) eLink clocks as the only clock in the ADC / QIE (sampling, internally multiplied for eLink transmission)
 - ◆ Implement a clock skew function in each ADC in order to align sampling to beam
 - Requires a control interface, e.g. i2c
- **Option 2**
 - ◆ Develop a clock fan-out chip with a clock skew function for each output
 - Here, the ADC is somewhat (but not much) simpler but an additional ASIC is required
- **Option 1 appears attractive as it safely solves essentially all problems with a smaller number of ASICs**